TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOS III)

# **TPC8211**

Lithium Ion Battery Applications Portable Equipment Applications Notebook PC Applications

• Low drain-source ON resistance:  $RDS(ON) = 25 \text{ m}\Omega \text{ (typ.)}$ 

• High forward transfer admittance:  $|Y_{fs}| = 7.0 \text{ S (typ.)}$ 

• Low leakage current:  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$ 

• Enhancement-mode:  $V_{th} = 1.3 \text{ to } 2.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$ 

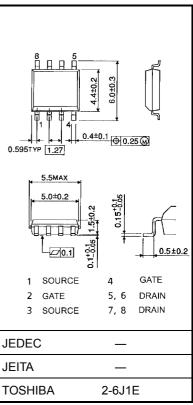
### **Maximum Ratings (Ta = 25°C)**

Char	racteristics	Symbol	Rating	Unit	
Drain-source vol	tage	$V_{DSS}$	30	V	
Drain-gate volta	ge (R <sub>GS</sub> = 20 kΩ)	$V_{DGR}$	30	V	
Gate-source volt	age	V <sub>GSS</sub>	±20	V	
Drain current	D C (Note 1)	I <sub>D</sub>	5.5	Α	
Drain current	Pulse (Note 1)	I <sub>DP</sub>	22	_ A	
Drain power dissipation	Single-device operation (Note 3a)	P <sub>D (1)</sub>	1.5	W	
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P <sub>D(2)</sub>	1.1		
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P <sub>D (1)</sub>	0.75	w	
	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.45	vv	
Single pulse ava	lanche energy (Note 4)	E <sub>AS</sub>	39.3	mJ	
Avalanche curre	nt	I <sub>AR</sub>	5.5	Α	
Repetitive avalar Single-device va	nche energy lue at dual operation (Note 2a, 3b, 5)	E <sub>AR</sub>	0.1	mJ	
Channel tempera	ature	T <sub>ch</sub>	150	°C	
Storage tempera	ture range	T <sub>stg</sub>	−55 to 150	°C	

Note: For (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5), please refer to the next page.

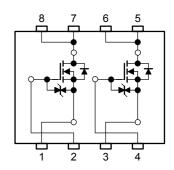
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm



Weight: 0.08 g (typ.)

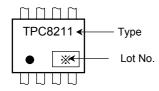
# **Circuit Configuration**



### **Thermal Characteristics**

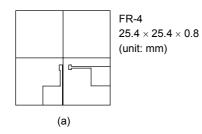
Characteristics	Symbol	Max	Unit		
The small resistance about 1 to embient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	83.3		
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	114	°C/W	
The weed we sintened a channel to crebine	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	167	C/VV	
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	278		

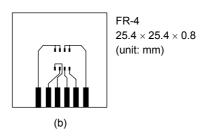
## Marking (Note 6)



Note 1: Please use devices on condition that the channel temperature is below 150°C.

#### Note 2:

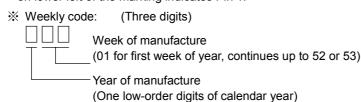




- a) Device mounted on a glass-epoxy board (a)
- b) Device mounted on a glass-epoxy board (b)

### Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device. (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device. (During dual operation, power is evenly applied to both devices.)
- Note 4:  $V_{DD}$  = 24 V,  $T_{ch}$  = 25°C (initial), L = 1.0 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 5.5 A
- Note 5: Repetitive rating: pulse width limited by maximum channel temperature
- Note 6: on lower left of the marking indicates Pin 1.



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# Electrical Characteristics (Ta = 25°C)

Characteristics Symbol Test Condition		Min	Тур.	Max	Unit		
Gate leakage cu	rrent	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$ — —		_	±10	μΑ
Drain cut-OFF	current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			10	μA
Drain-source breakdown voltage		V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	= 10 mA, V <sub>GS</sub> = 0 V 30 -	_	_	V
		V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V	15	_	_	
Gate threshold v	roltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.3	_	2.5	V
Drain-aguras O	N registance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 3 A	_	31	44	m0
Drain-source ON resistance		R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A	_	25	36	mΩ
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3 A	3.5	7.0	_	S
Input capacitano	е	C <sub>iss</sub>		_	1250	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	155	_	pF
Output capacitance		C <sub>oss</sub>		_	170	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10 \text{ V}}{\underset{O \text{ V}}{\bigcap}} \stackrel{I_D = 3 \text{ A}}{\underset{O \text{ C}}{\bigcap}} V_{OUT}$ $V_{D} = 15 \text{ V}$	_	5	_	
	Turn-ON time	t <sub>on</sub>			11	_	ne
	Fall time	t <sub>f</sub>		1	9		ns
	Turn-OFF time	t <sub>off</sub>	Duty $\leq$ 1%, $t_W = 10 \mu s$	l	63		
Total gate charge (Gate-source plus gate-drain)		$Q_{g}$	V <sub>DD</sub> ≈ 24 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5.5 A	_	25	_	
Gate-source charge		Q <sub>gs</sub>		_	20	_	nC
Gate-drain ("miller") charge		$Q_{gd}$		_	5	_	

# **Source-Drain Ratings and Characteristics (Ta = 25°C)**

Characte	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	22	Α
Forward voltage (	vard voltage (diode) V <sub>DSF</sub> I <sub>DR</sub> = 5.5 A, V <sub>GS</sub> = 0 V —		_	_	-1.2	V	

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